

ficonteC

EPIC Online Technology Meeting on
Photonics Packaging and Testing

Torsten Vahrenkamp

Multi-Solution from One Source

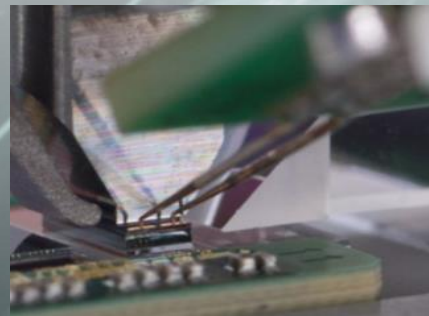
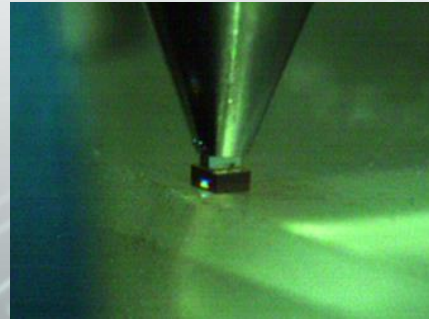
Laser Diode Stacking Testing & Characterisation

- Stacking unstacking
- LD/LD bar handling
- Facet coating
- Visual inspection



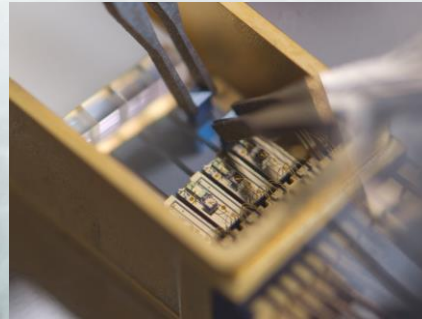
Laser and PD Die Bonding

- Laser diodes/photo diodes
- Passive/active
- Integrated optics
- Laser soldering
- Conventional heating



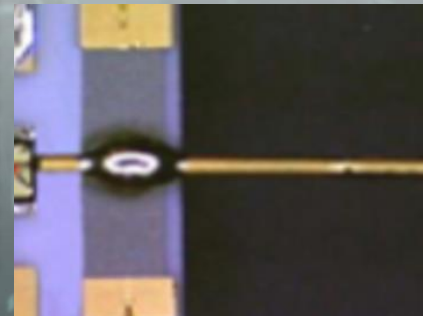
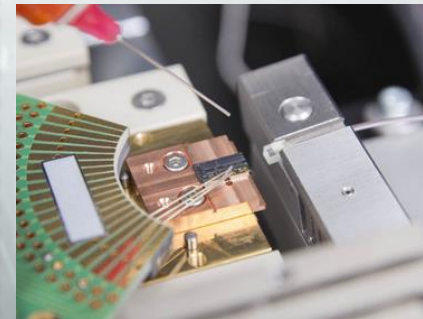
Lens Attach and Complex Optical Subassemblies

- Active alignment
- Lens and array assembly
- Epoxy bonding
- Thermal cure
- Different dispensing methods
- Full/semi automatic



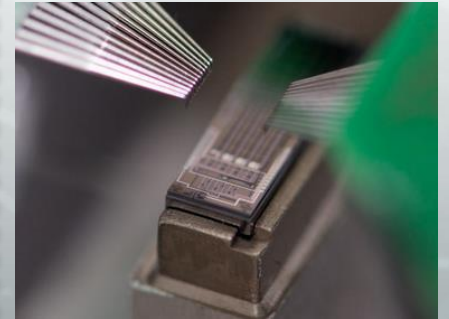
Fiber Attach Processes

- Fiber to pump assembly
- Fiber array attachment
- Automatic fiber handling
- Laser welding
- Laser soldering

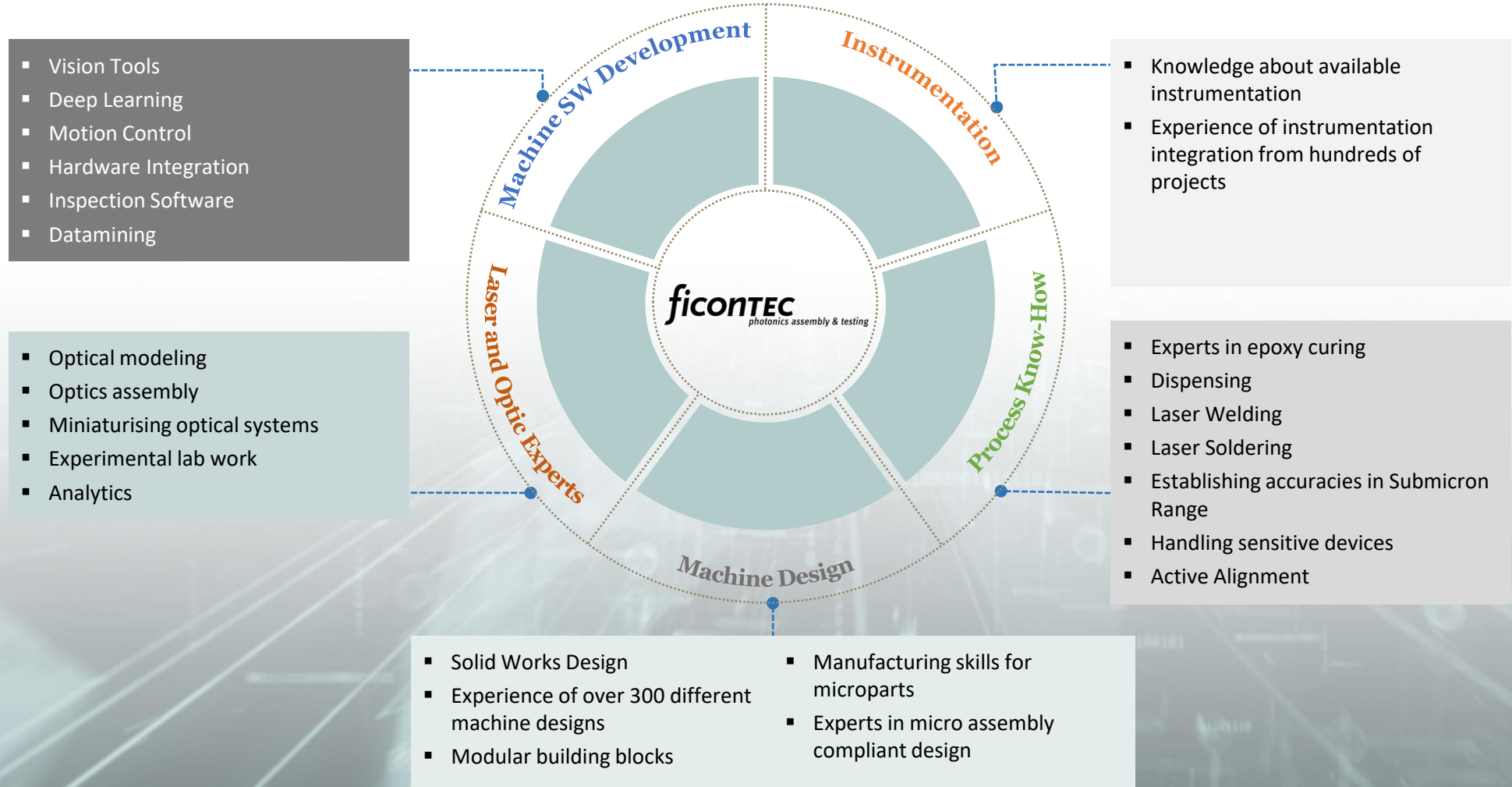


Test/ Characterisation

- Final module test
- Chip Test
- Wafer Level Test
- Handling to/from burn in carrier
- Supply of customised test equipment based on PXI



We Build Machines – Core Knowhow



The machine is the physical manifestation of the process

From Prototype Machines to Mass Production



Fully automated Production Line consisting of several Feeders, Passive and Active Attachment, EoL test and Laser marking

Automated Production System consisting of 1 Input Feeder; 1 Systems; 1 Output Feeder



Production System with Development capability



Lab System with Production capability



Global Presence – Think Global Act Local

20years of experience



THANK YOU !

Torsten.Vahrenkamp@ficontec.com

ficonTEC Service GmbH - Rehland 8, 28832 Achim / Germany
www.ficontec.com